IPC  ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard  Form Type http://www.ipc.org/IPC-175x  Form Type Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials						g Info	ormation			
upplier Inform	nation															
Company name* Company unique ID				ue ID	Unique ID Authority				Response Date*							
nsemi												2024-04-25				
ontact Name		Title	Fitle - Contact			I	Phone - Contact*				Email - Contact*					
Product-Env-Stewa	ards	Prod	duct Enviro	nviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative*  Title - Representative				ntative		Phone - Representative*				·	Email - Representative*					
Product-Env-Stewards Product Enviro Con				Compliance	iance NA						Product-Env-Stewards@onsemi.com					
Requeste	er Item Number	Mfr Item Num	n Number Mfr Item Name				Effective Date   Version		ion	Manufacturing Site		W	eight	t* U	OM	Unit Type
	1	NOIX4SP3000	X4SP3000B-LTI XGS3MP, 4.7CRA, 16port			no	2024-04-25		7	TA1			189.09	9 m	g	Each
<b>Ianufacturing</b>	Proccess Information							<u> </u>								
Terminal	Terminal Plating / Grid Array Material		Terminal Base Alloy J-		STD-020 MSL Rating		Peak Pro	Peak Process Body Temperature		re Max Time at Peak Tempera		Temperatu	re N	re Number of Reflow Cycles		les
Precious Sn)	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		lloy 4			<b>245</b> C		30		second	seconds 3					
omments			·		·		· ·	·	· ·							·
				page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shave provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	220.55	mg		Misc.	proprietary data		0.8381	mg
			Supplier	Silicon (Si)	7440-21-3		217.5285	mg
			Supplier	Aluminum (Al)	7429-90-5		2.1834	mg
Die Attach Epoxy	45.39	mg	Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		34.0425	mg
			Supplier	Imidazole Addition	68490-66-4		1.3617	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		6.8085	mg
			Supplier	Silica (SiO2)	14464-46-1		3.1773	mg
Imaging Lens	456.52	mg	Supplier	Sulfur (S)	7704-34-9		2.2826	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		22.826	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		22.826	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		22.826	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		22.826	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		22.826	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		22.826	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		317.2814	mg
Lid Attach	5.77	mg		Epoxy resin	proprietary data		4.6679	mg
			Supplier	Adeka Optomer SP 150	125054-47-9		0.1385	mg
			Supplier	Photoinitiator	Proprietary Data		0.427	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5366	mg
Mold Compound-Black	256.37	mg		Phenolic Resin	proprietary data		38.4555	mg
			Supplier	Oxirane	39817-09-9		38.4555	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		7.6911	mg
			Supplier	Carbon Black (C)	1333-86-4		2.5637	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		164.0768	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5.1274	mg
Substrate	202.55	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		42.9406	mg
			Supplier	Inorganic filler	Proprietary Data		26.4935	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		2.6534	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.6482	mg
			Supplier	Acetophenone Derivative	Proprietary Data		3.97	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6684	mg

				2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.6684	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	7.94	mg
			Supplier	Copper (Cu)	7440-50-8	96.0492	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	20.5183	mg
Wire Bond - Au	1.94	mg	Supplier	Gold (Au)	7440-57-5	1.94	mg